OptiMOS® Power-Transistor

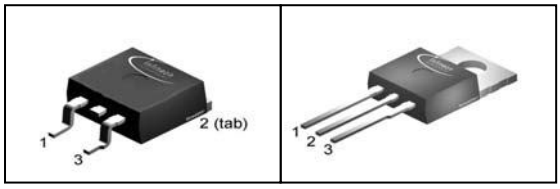
Features

- N-channel Logic Level - Enhancement mode
- Automotive AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green package (lead free)
- Ultra low Rds(on)
- 100% Avalanche tested

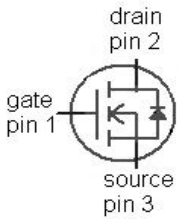
Product Summary

V_{DS}	55	V
$R_{DS(on),max}$ (SMD version)	6.7	mΩ
I_D	80	A

PG-TO263-3-2 PG-TO220-3-1



Type	Package	Ordering Code	Marking
IPB80N06S2L-07	PG-TO263-3-2	SP0002-18867	2N06L07
IPP80N06S2L-07	PG-TO220-3-1	SP0002-18831	2N06L07



Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current[1]	I_D	T_C=25 °C, V_{GS}=10 V	80	A
		T_C=100 °C, V_{GS}=10 V[2]	80	
Pulsed drain current[2]	$I_{D,pulse}$	T_C=25 °C	320	
Avalanche energy, single pulse[2]	E_{AS}	I_D= 80 A	450	mJ
Gate source voltage[4]	V_{GS}		±20	V
Power dissipation	P_{tot}	T_C=25 °C	210	W
Operating and storage temperature	T_j, T_{stg}		-55 ... +175	°C

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics[2]						
Thermal resistance, junction - case	R_{thJC}		-	-	0.7	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}		-	-	62	
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm^2 cooling area[5]	-	-	40	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D= 1 mA	55	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=150 µA	1.2	1.6	2.0	
Zero gate voltage drain current	I_{DSS}	V_{DS}=55 V, V_{GS}=0 V, T_j=25 °C	-	0.01	1	µA
		V_{DS}=55 V, V_{GS}=0 V, T_j=125 °C[2]	-	1	100	
Gate-source leakage current	I_{GSS}	V_{GS}=20 V, V_{DS}=0 V	-	1	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=4.5 V, I_D=60 A	-	7.1	10	mΩ
		V_{GS}=4.5 V, I_D=60 A, SMD version	-	6.8	9.7	
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10 V, I_D=60 A,	-	5.6	7.0	mΩ
		V_{GS}=10 V, I_D=60 A, SMD version	-	5.3	6.7	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics[2]						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=25 V, f=1 MHz	-	3160	-	pF
Output capacitance	C_{oss}		-	740	-	
Reverse transfer capacitance	C_{rss}		-	210	-	
Turn-on delay time	$t_{d(on)}$	V_{DD}=30 V, V_{GS}=10 V, I_D=80 A, R_G=2 Ω	-	18	-	ns
Rise time	t_r		-	35	-	
Turn-off delay time	$t_{d(off)}$		-	28	-	
Fall time	t_f		-	31	-	
Gate Charge Characteristics[2]						
Gate to source charge	Q_{gs}	V_{DD}=44 V, I_D=80 A, V_{GS}=0 to 10 V	-	11	14	nC
Gate to drain charge	Q_{gd}		-	32	48	
Gate charge total	Q_g		-	95	130	
Gate plateau voltage	$V_{plateau}$		-	3.5	-	V
Reverse Diode						
Diode continous forward current[2]	I_S	T_C=25 °C	-	-	80	A
Diode pulse current[2]	$I_{S,pulse}$		-	-	320	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=80 A, T_j=25 °C	-	0.9	1.3	V
Reverse recovery time[2]	t_{rr}	V_R=30 V, I_F=I_S, di_F/dt=100 A/µs	-	59	75	ns
Reverse recovery charge[2]	Q_{rr}		-	80	100	nC

[1] Current is limited by bondwire; with an R_{thJC} = 0.7 K/W the chip is able to carry 121 A at 25°C. For detailed information see Application Note ANPS071E at *www.infineon.com/optimos*

[2] Defined by design. Not subject to production test.

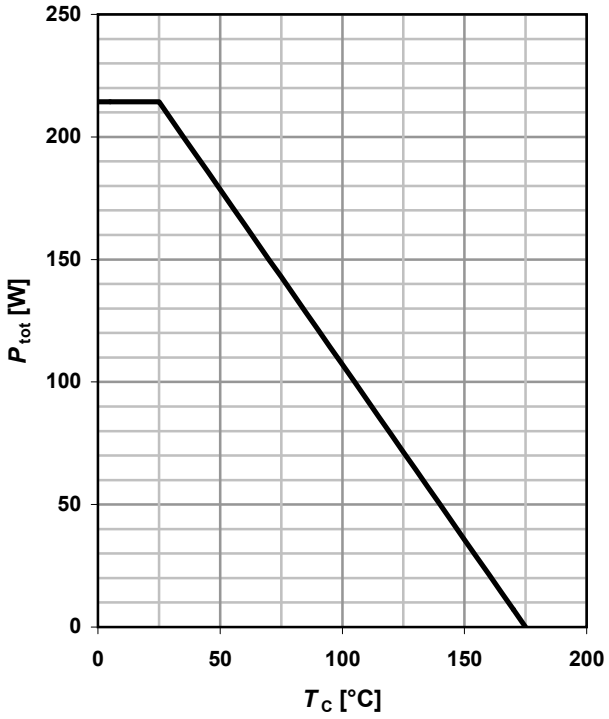
[3] See diagram 13

[4] Qualified at -20V and +20V.

[5] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

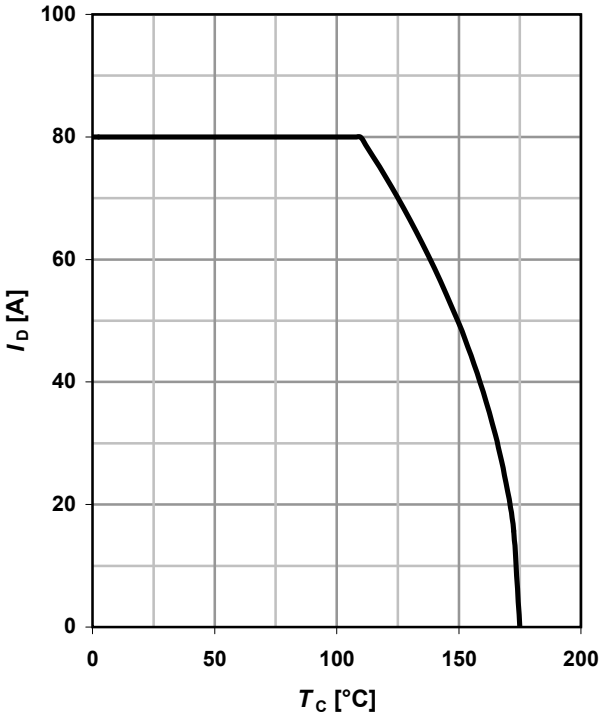
1 Power dissipation

$P_{tot} = f(T_C)$; $V_{GS} \geq 4$ V



2 Drain current

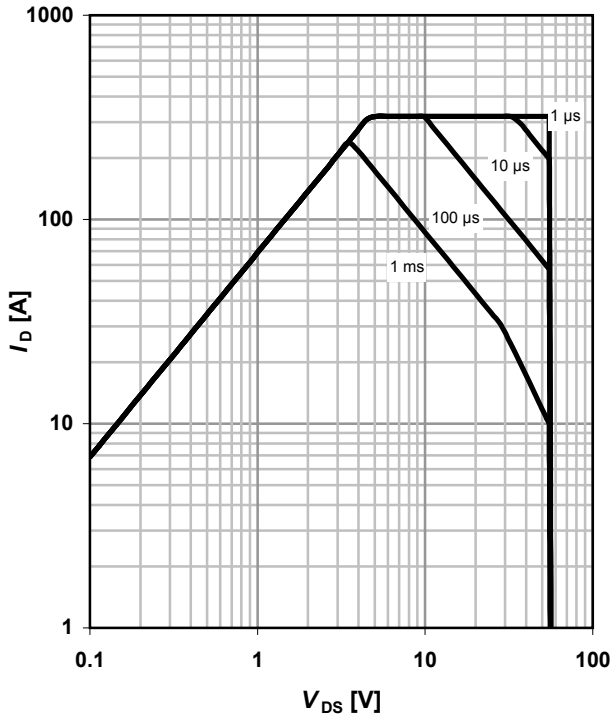
$I_D = f(T_C)$; $V_{GS} \geq 10$ V



3 Safe operating area

$I_D = f(V_{DS})$; $T_C = 25$ °C; $D = 0$

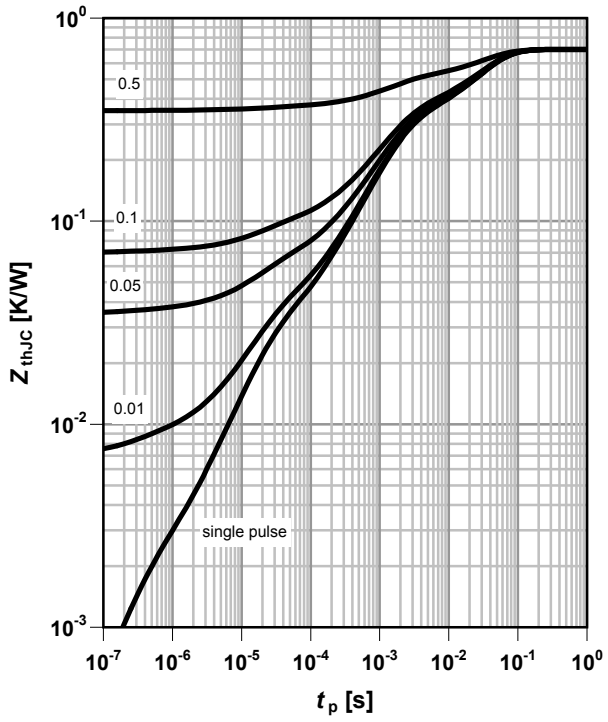
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

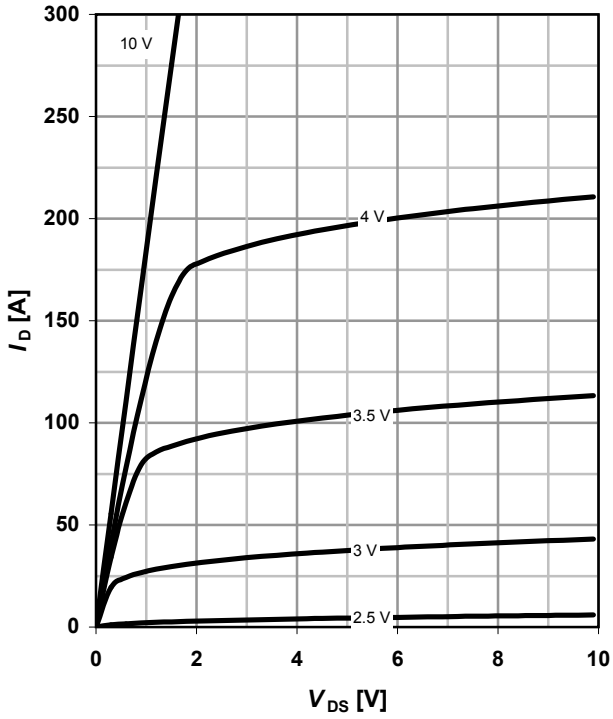
parameter: $D = t_p / T$



5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25$ °C

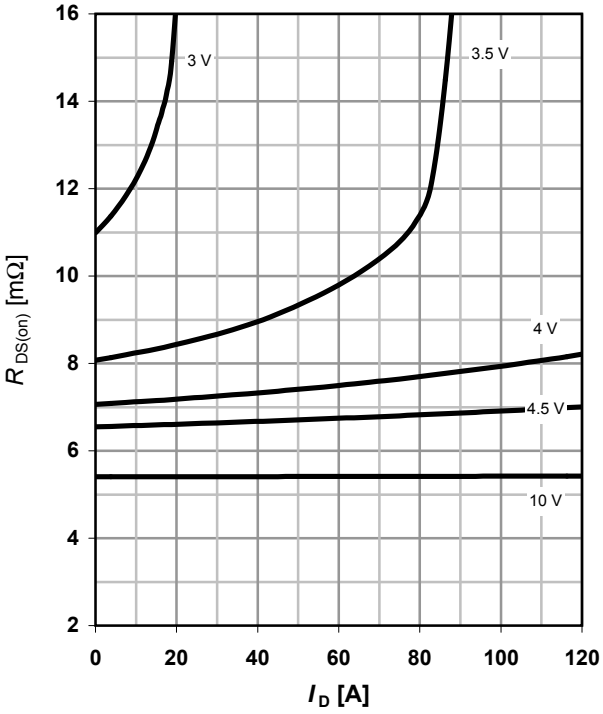
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = (I_D)$; $T_j = 25$ °C

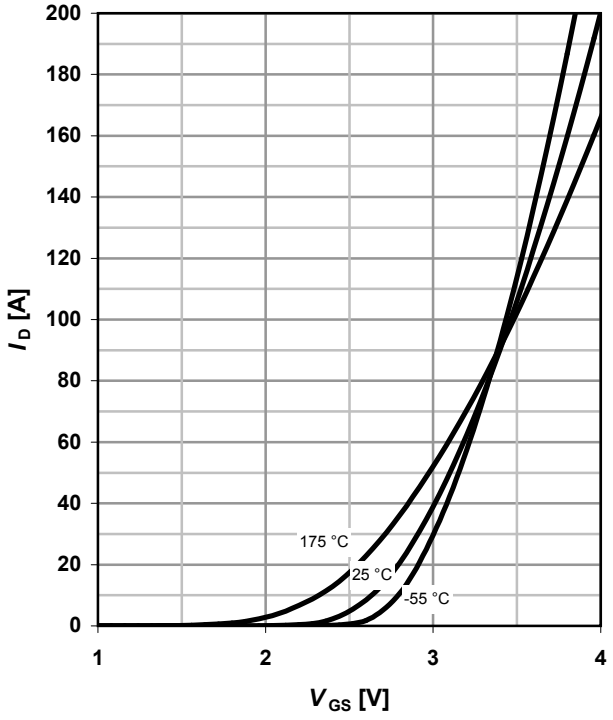
parameter: V_{GS}



7 Typ. transfer characteristics

$I_D = f(V_{GS})$; $V_{DS} = 6$V

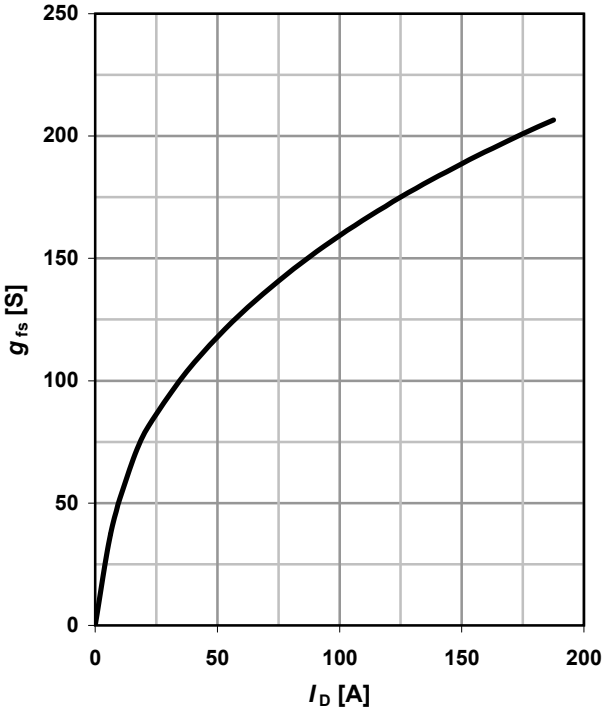
parameter: T_j



8 Typ. Forward transconductance

$g_{fs} = f(I_D)$; $T_j = 25$°C

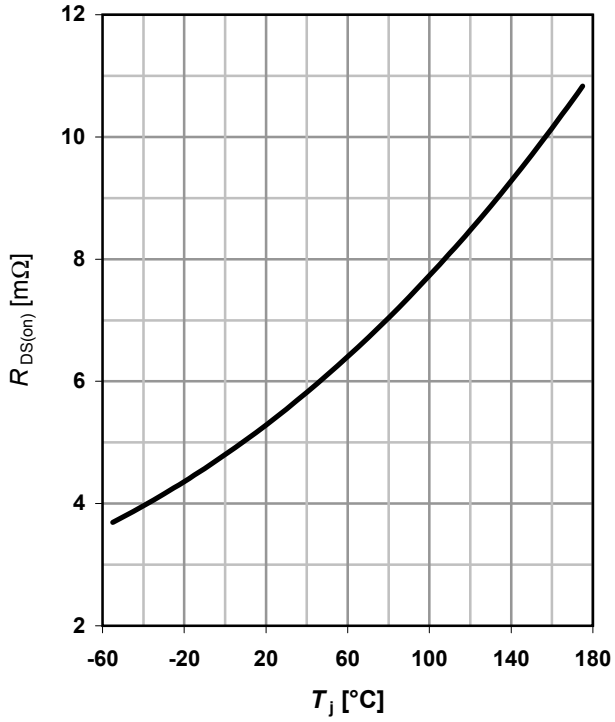
parameter: g_{fs}



9 Typ. Drain-source on-state resistance

$R_{DS(ON)} = f(T_j)$

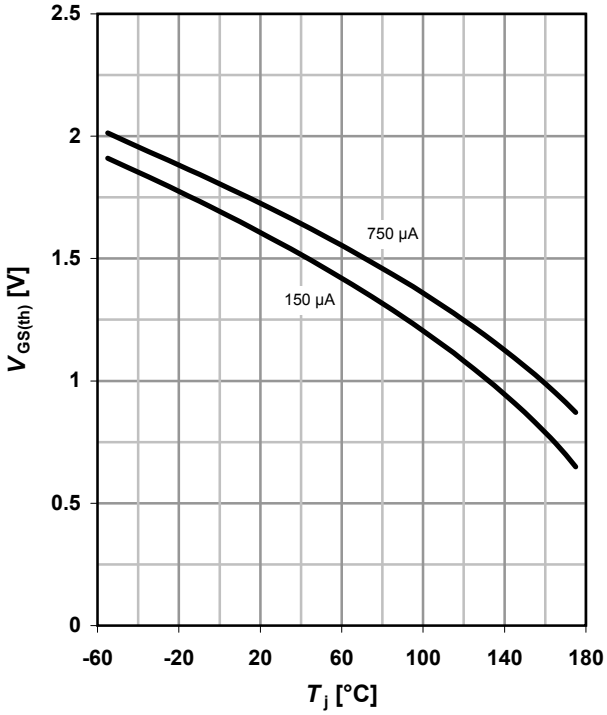
parameter: $I_D = 80$ A; $V_{GS} = 10$ V



10 Typ. gate threshold voltage

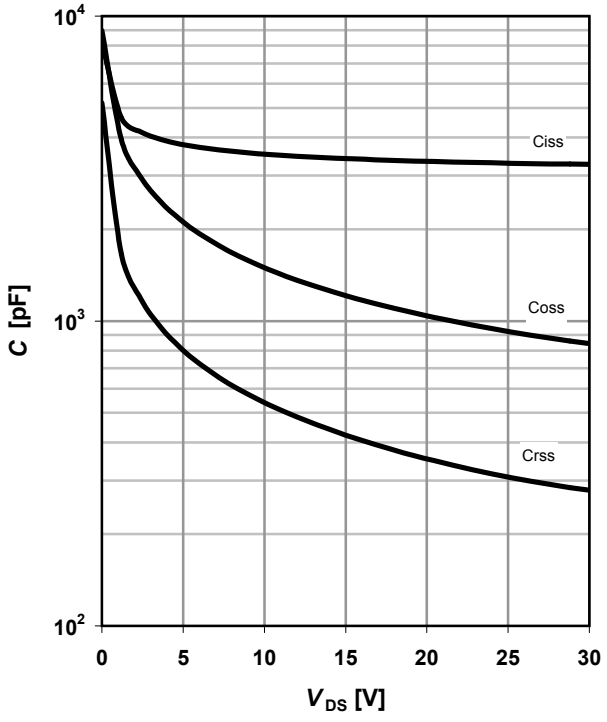
$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$

parameter: I_D



11 Typ. capacitances

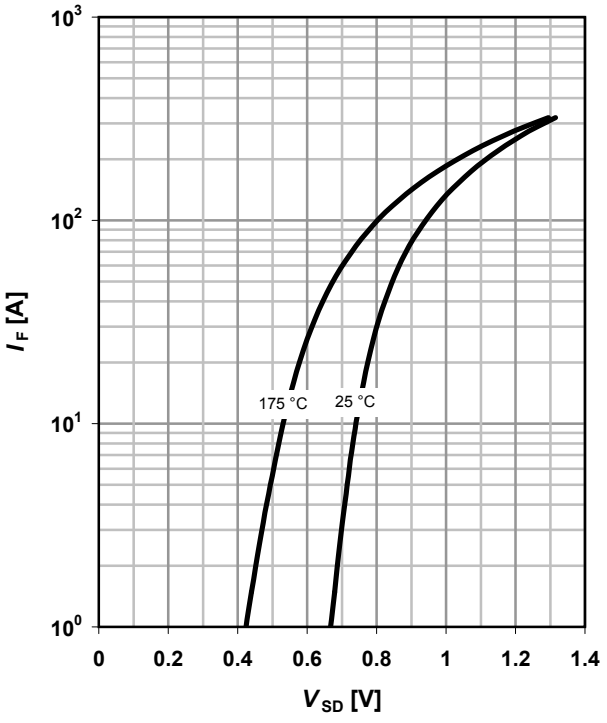
$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz



12 Typical forward diode characteristicis

IF = f(V_{SD})

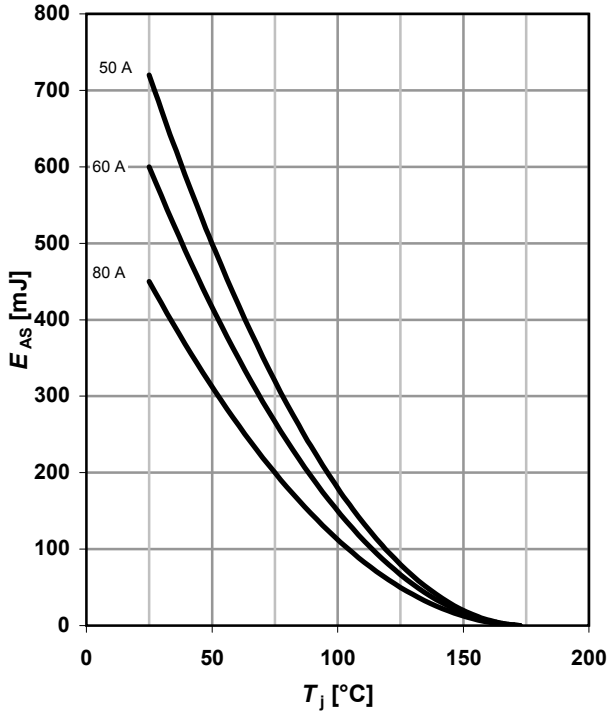
parameter: T_j



13 Typical avalanche energy

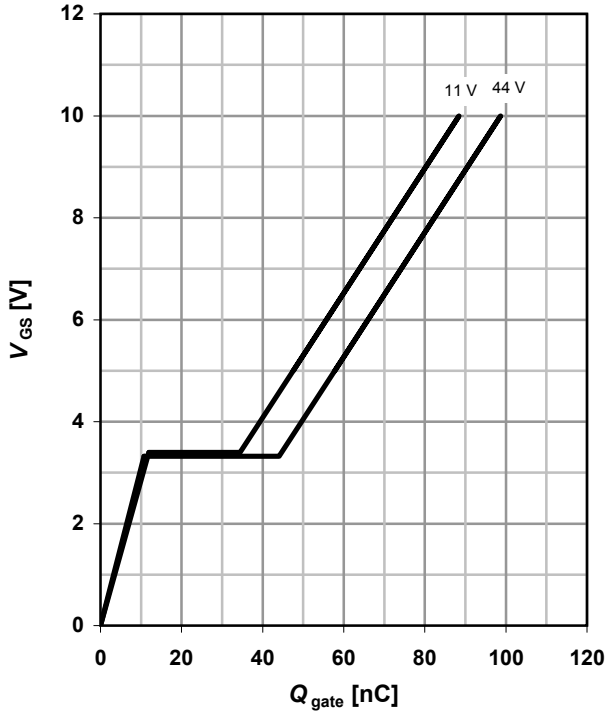
$E_{AS} = f(T_j)$

parameter: I_D



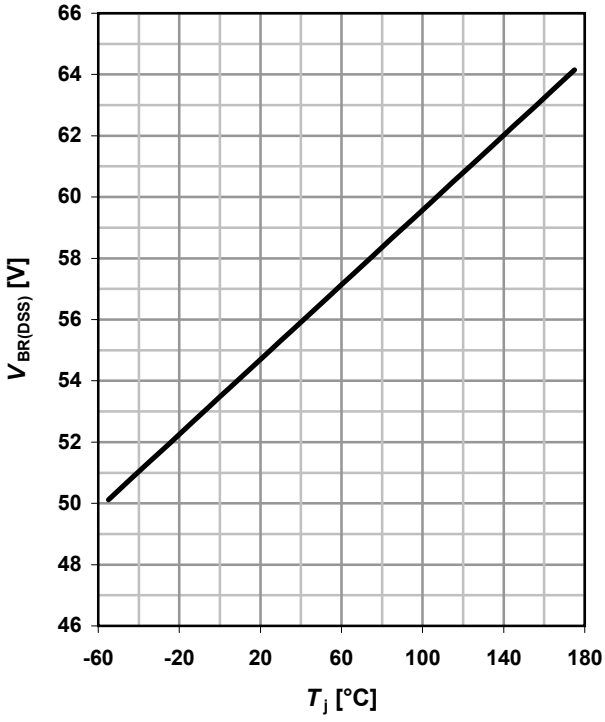
14 Typ. gate charge

$V_{GS} = f(Q_{gate})$; $I_D = 80$ A pulsed

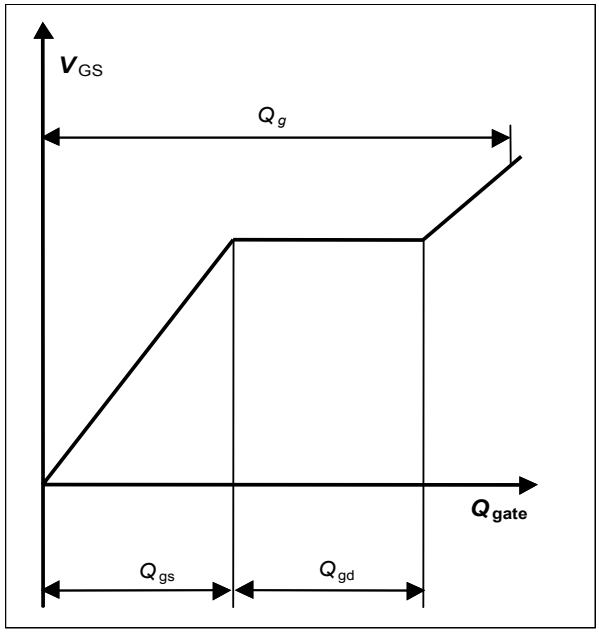


15 Typ. drain-source breakdown voltage

$V_{BR(DSS)} = f(T_j)$; $I_D = 1$ mA



16 Gate charge waveforms



Published by
Infineon Technologies AG
St.-Martin-Straße 53
D-81541 München

Attention please!
The information herein is given to describe certain components and shall not be considered as a guarantee of characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Information
For further information on technology, delivery terms and conditions and prices, please contact your nearest Infineon Technologies Office (www.infineon.com)

Warnings
Due to technical requirements, components may contain dangerous substances.
For information on the types in question, please contact your nearest Infineon Technologies Office.

effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.